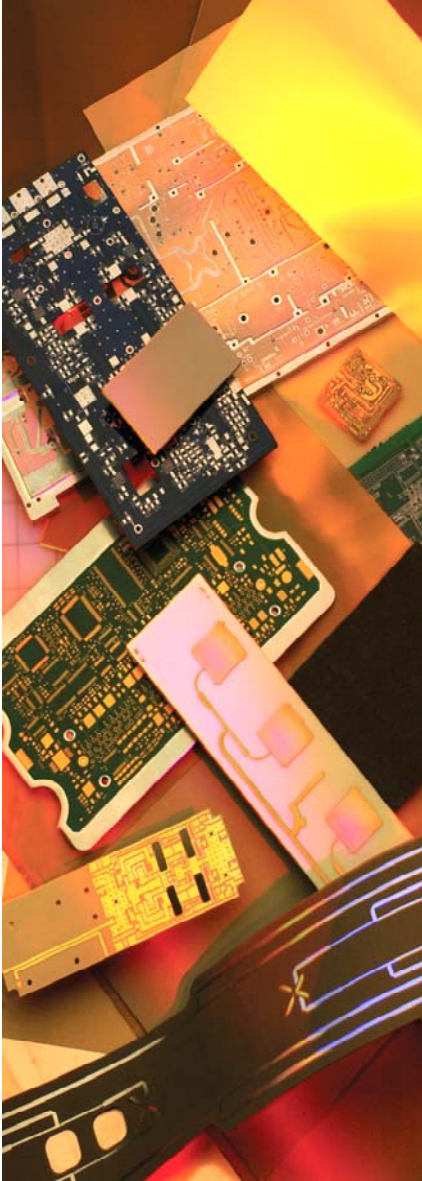


POLYIMIDE LAMINATE AND PREPREG



33N is a flame retardant (UL-94 V0) polyimide laminate and prepreg system where the excellent high performance properties of polyimide need to be combined with flame retardance. High TG (250°C) results in low overall processing, and minimizes risk of latent PTH defects in-service.

Features:

- Tg greater than 250°C
- Certified to the flammability requirements of UL-94 V-0
- Low Z-expansion of 1.2% between 50-260°C (vs. 2.5-4.0% for typical high-performance epoxies)
- Low-Z expansion minimizes the risk of PTH latent defects caused during solder reflow and device attachment
- Decomposition temperature of 390°C (vs. 300-360°C for typical high-performance epoxies) offering outstanding long term high-temperature performance
- Electrical and mechanical properties meeting the requirements of IPC-4101/40 and /41
- Toughened, Non-MDA chemistry resists drill cracking
- Compatible with lead-free processing
- RoHS/WEEE compliant

Typical Applications:

- PCBs that are subjected to high temperatures during processing, such as lead-free soldering
- Applications with significant lifetimes at high temperatures, such as aircraft engine instrumentation, down hole drilling, under-hood automotive controls, burn-in boards, or industrial sensors.

Typical Properties:



Property	Units	Value	Test Method
1. Electrical Properties			
Dielectric Constant			
@ 1 MHz	-	4.0	IPC TM-650 2.5.5.3
@ 1 GHz	-		IPC TM-650 2.5.5.9
Dissipation Factor			
@ 1 MHz	-	0.01	IPC TM-650 2.5.5.3
@ 1 GHz	-		IPC TM-650 2.5.5.9
Volume Resistivity		7.3	
C96/35/90	MΩ-cm	7.2×10^7	IPC TM-650 2.5.17.1
E24/125	MΩ-cm	4.5×10^8	IPC TM-650 2.5.17.1
Surface Resistivity			
C96/35/90	MΩ	4.1×10^8	IPC TM-650 2.5.17.1
E24/125	MΩ	1.6×10^9	IPC TM-650 2.5.17.1
Electrical Strength (typical)	Volts/mil (kV/mm)	1290 (50.8)	IPC TM-650 2.5.6.2
Dielectric Breakdown	kV		IPC TM-650 2.5.6
Arc Resistance	sec	170	IPC TM-650 2.5.1
2. Thermal Properties			
Glass Transition Temperature (Tg)			
TMA	°C	>250	IPC TM-650 2.4.24
DSC	°C		IPC TM-650 2.4.25
Decomposition Temperature (Td)			
Initial	°C	353	IPC TM-650 2.4.24.6
5%	°C	389	IPC TM-650 2.4.24.6
T260	min	>60	IPC TM-650 2.4.24.1
T288	min	23	IPC TM-650 2.4.24.1
T300	min	8	IPC TM-650 2.4.24.1
CTE (x,y)	ppm/°C	16	IPC TM-650 2.4.41
CTE (z)			IPC TM-650 2.4.24
< Tg	ppm/°C	53	IPC TM-650 2.4.24
> Tg	ppm/°C	164	IPC TM-650 2.4.24
z-axis Expansion (50-260°C)	%	1.2	IPC TM-650 2.4.24
3. Mechanical Properties			
Peel Strength to Copper (1 oz/35 micron)			
After Thermal Stress	lb/in (N/mm)	7.2 (1.2)	IPC TM-650 2.4.8
At Elevated Temperatures	lb/in (N/mm)	7.2 (1.2)	IPC TM-650 2.4.8.2
After Process Solutions	lb/in (N/mm)	7.5 (1.3)	IPC TM-650 2.4.8
Young's Modulus	Mpsi (GPa)	3.2	IPC TM-650 2.4.18.3
Flexural Strength	kpsi (MPa)		IPC TM-650 2.4.4
Tensile Strength	kpsi (MPa)		IPC TM-650 2.4.18.3
Compressive Modulus	kpsi (MPa)		ASTM D-695
Poisson's Ratio (x, y)	-	0.15	ASTM D-3039
4. Physical Properties			
Water Absorption	%	0.21	IPC TM-650 2.6.2.1
Specific Gravity	g/cm ³	1.6	ASTM D792 Method A
Thermal Conductivity	W/mk	0.2	ASTM E1461
Flammability	class	V-0	UL-94

Availability:

Arlon Part Number	Glass Style	Resin %	Scaled Flow Hf (mils)	Scaled Flow ΔH (mils)
33N0672	106	72 \pm 3	1.9 \pm 0.3	0.55 \pm 0.20
33N8063	1080	63 \pm 3	2.6 \pm 0.3	0.55 \pm 0.20
33N2355	2313	55 \pm 3	3.6 \pm 0.3	0.55 \pm 0.20
33N2650	2116	50 \pm 3	4.3 \pm 0.3	0.55 \pm 0.20
33N2840	7628	40 \pm 3	6.8 \pm 0.3	0.55 \pm 0.20

Recommended Process Conditions:

Process inner-layers through develop, etch, and strip using standard industry practices. Use brown oxide on inner layers. Adjust dwell time in the oxide bath to ensure uniform coating. Bake inner layers in a rack for 60 minutes at 225°F - 250°F (107°C - 121°C) immediately prior to lay-up. Vacuum desiccate the prepreg for 8 - 12 hours prior to lamination.

Lamination Cycle:

- 1) Pre-vacuum for 30 - 45 minutes
- 2) Control the heat rise to 8°F - 12°F (4°C - 6°C) per minute between 150°F and 250°F (65°C and 121°C)

Panel Size		Pressure	
in	cm	psi	kg/sq cm
12 x 18	40 x 46	275	19
16 x 18	30 x 46	350	25
18 x 24	46 x 61	400	28

- 3) Product temperature at start of cure = 410°F (218°C).
- 4) Cure time at temperature = 90 minutes
NOTE: For sequential lamination use 60 minutes for the first lamination and 90 minutes for the final.
- 3) Cool down under pressure at \leq 12°F/min (6°C/min)

Drill at 350 SFM. Undercut bits are recommended for vias 0.018" and smaller

De-smear using alkaline permanganate or plasma with settings appropriate for polyimide; plasma is preferred for positive etchback

Conventional plating processes are compatible with 33N

Standard profiling parameters may be used; chip breaker style router bits are not recommended

Bake for 1 - 2 hours at 250°F (121°C) prior to solder to reflow of HASL

33N

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